

10/581657

Express Mail Mailing Label No. 689988641 US

AP3 Rec'd PCT/PTO 01 JUN 2005 PATENT

Attorney Docket No. GWS-005
(104023 /143729)

Particulars of prior application:

International Serial No. PCT/US2004/040698

International Filing Date: December 3, 2004

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: Okada et al.
SERIAL NO.: Not yet assigned GROUP NO.: Not yet assigned
FILING DATE: Herewith EXAMINER: Not yet assigned
TITLE: SYSTEM AND METHOD TO REDUCE METAL SERIES RESISTANCE
OF BUMPED CHIP

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

PRELIMINARY AMENDMENT

Please enter the following Preliminary Amendment before beginning examination of the above-referenced patent application.

Please amend the above-identified patent application as follows:

Amendments to the Specification begin on page 2 of this paper;

Amendments to the Claims are reflected in the listing of claims that begins on page 3 of this paper; and

Remarks begin on page 7 of this paper.